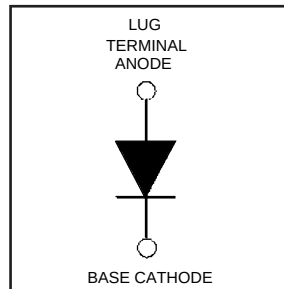


HFA90NH40

Ultrafast, Soft Recovery Diode

Features

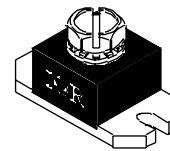
- Reduced RFI and EMI
- Reduced Snubbing
- Extensive Characterization of Recovery Parameters



$V_R = 400V$
$V_F(\text{typ.}) \textcircled{3} = 1V$
$I_{F(AV)} = 90A$
$Q_{rr}(\text{typ.}) = 420nC$
$I_{RRM}(\text{typ.}) = 9.3A$
$t_{rr}(\text{typ.}) = 36ns$
$di_{(rec)M}/dt(\text{typ.}) \textcircled{3} = 260A/\mu s$

Description

HEXFRED™ diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and di/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.



HALF-PAK

Absolute Maximum Ratings (per Leg)

	Parameter	Max.	Units
V_R	Cathode-to-Anode Voltage	400	V
$I_F @ T_C = 25^\circ C$	Continuous Forward Current	170	A
$I_F @ T_C = 100^\circ C$	Continuous Forward Current	84	
I_{FSM}	Single Pulse Forward Current ^①	600	
E_{AS}	Non-Repetitive Avalanche Energy ^②	1.4	mJ
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	310	W
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	125	
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	°C

Thermal - Mechanical Characteristics

	Parameter	Min.	Typ.	Max.	Units
R_{thJC}	Junction-to-Case	-----	-----	0.40	°C/W
R_{thCS}	Case-to-Sink, Flat, Greased Surface	-----	0.15	-----	K/W
Wt	Weight	-----	26 (0.9)	-----	g (oz)
	Mounting Torque ^④	15 (1.7)	-----	25 (2.8)	lbf•in
	Terminal Torque	30 (3.4)	-----	40 (4.6)	(N•m)
	Vertical Pull	-----	-----	35	lbf•in
	2 inch Lever Pull	-----	-----	35	

Note: ^① Limited by junction temperature
^② L = 100μH, duty cycle limited by max T_J
^③ 125°C

^④ Mounting surface must be smooth, flat, free of burrs or other protrusions. Apply a thin even film of thermal grease to mounting surface. Gradually tighten each mounting bolt in 5-10 lbf•in steps until desired or maximum torque limits are reached. Module

HFA90NH40

PD-2.468 rev. B 02/99

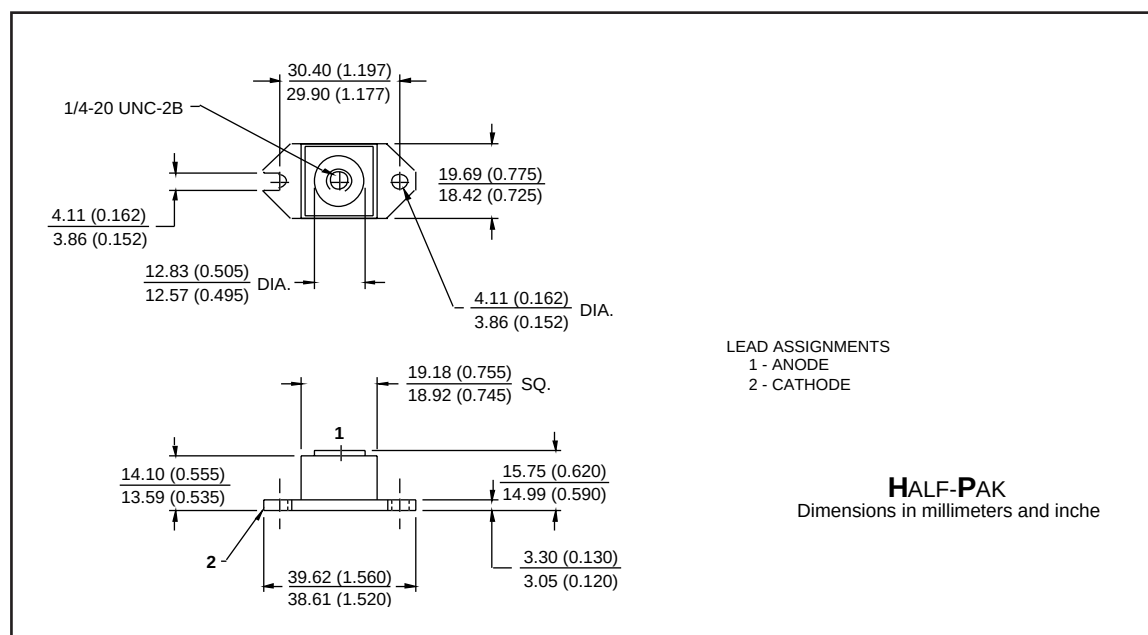
International
IOR Rectifier

Electrical Characteristics (per Leg) @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Parameter	Min.	Typ.	Max.	Units	Test Conditions
V_{BR} Cathode Anode Breakdown Voltage	400	—	—	V	$I_R = 100\mu\text{A}$
V_{FM} Max Forward Voltage See Fig. 1	—	1.1	1.3	V	$I_F = 90\text{A}$
	—	1.3	1.5		$I_F = 180\text{A}$
	—	1.0	1.2		$I_F = 90\text{A}, T_J = 125^\circ\text{C}$
I_{RM} Max Reverse Leakage Current See Fig. 2	—	1.0	6.0	μA	$V_R = V_R \text{ Rated}$
	—	1.5	8.0	mA	$T_J = 125^\circ\text{C}, V_R = 320\text{V}$
C_T Junction Capacitance See Fig. 3	—	180	260	pF	$V_R = 200\text{V}$
L_S Series Inductance	—	7.0	—	nH	From top of terminal hole to mounting plane

Dynamic Recovery Characteristics (per Leg) @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Parameter	Min.	Typ.	Max.	Units	Test Conditions
t_{rr} Reverse Recovery Time See Fig. 5	—	36	—	ns	$I_F = 1.0\text{A}, di_f/dt = 200\text{A}/\mu\text{s}, V_R = 30\text{V}$
t_{rr1}	—	90	140		$T_J = 25^\circ\text{C}$
t_{rr2}	—	160	240		$T_J = 125^\circ\text{C}$
I_{RRM1} Peak Recovery Current See Fig. 6	—	9.3	17	A	$T_J = 25^\circ\text{C}$
I_{RRM2}	—	15	30		$T_J = 125^\circ\text{C}$
Q_{rr1} Reverse Recovery Charge See Fig. 7	—	420	1100	nC	$T_J = 25^\circ\text{C}$
Q_{rr2}	—	1200	3200		$T_J = 125^\circ\text{C}$
$di_{(rec)M}/dt1$ Peak Rate of Fall of Recovery Current During t_b See Fig. 8	—	360	—	$\text{A}/\mu\text{s}$	$T_J = 25^\circ\text{C}$
$di_{(rec)M}/dt2$	—	260	—		$T_J = 125^\circ\text{C}$



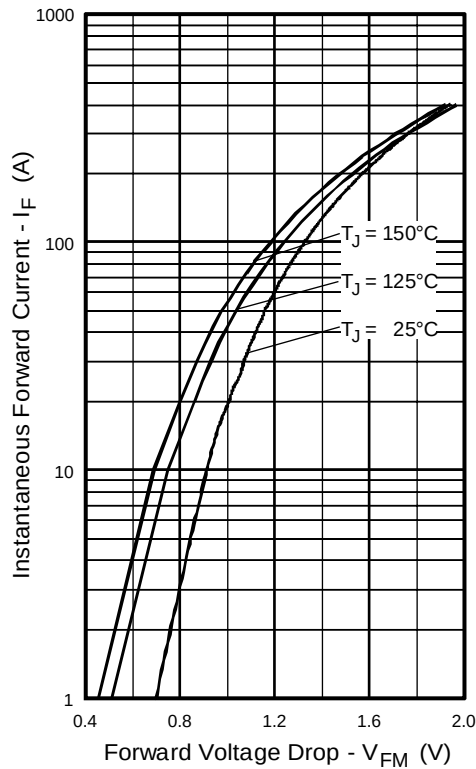


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

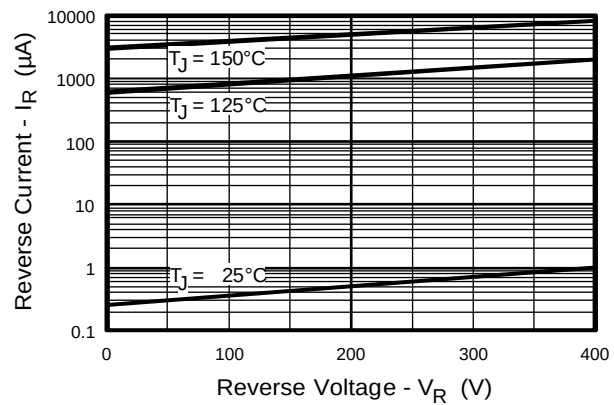


Fig. 2 - Typical Reverse Current vs. Reverse Voltage

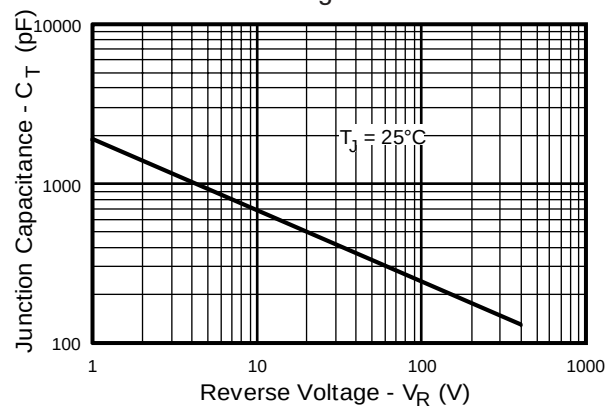


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

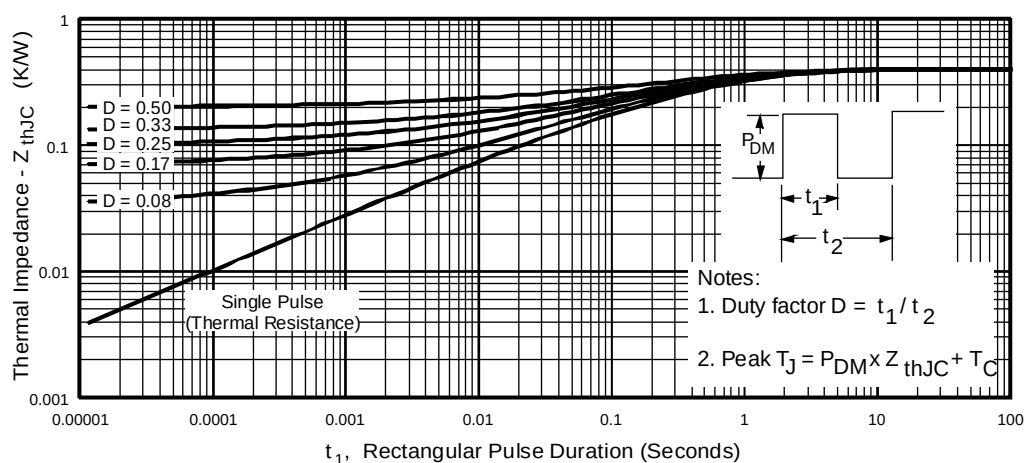


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

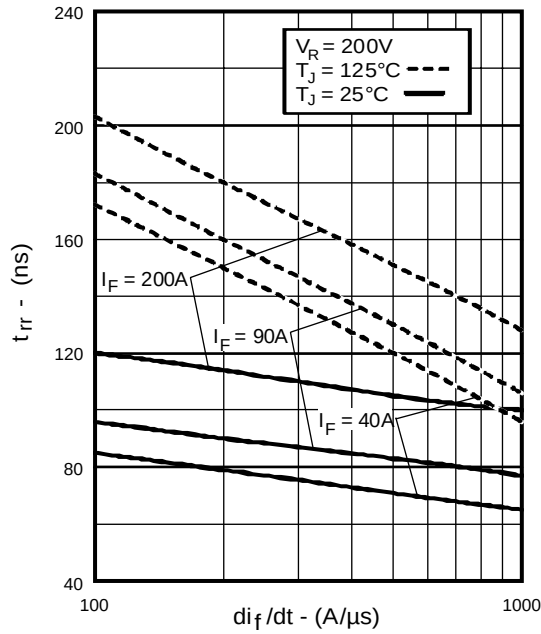


Fig. 5 - Typical Reverse Recovery vs. di_f/dt

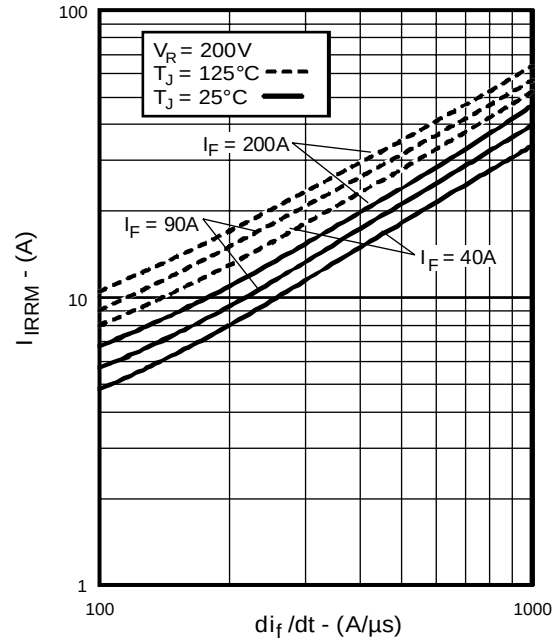


Fig. 6 - Typical Recovery Current vs. di_f/dt

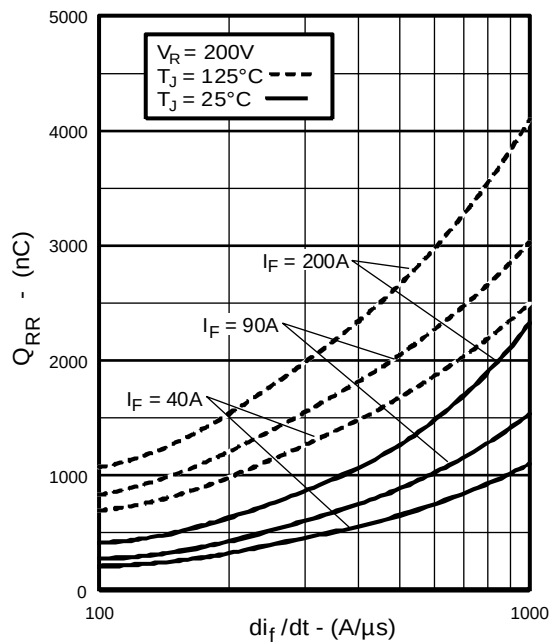


Fig. 7 - Typical Stored Charge vs. di_f/dt

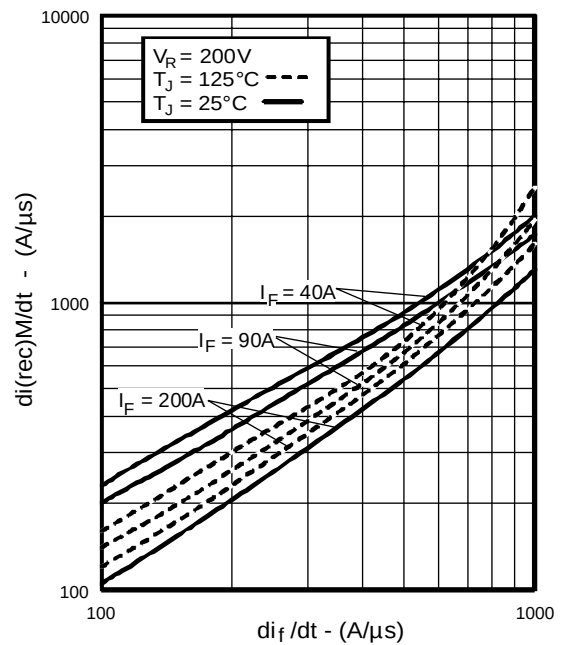


Fig. 8 - Typical $di_{(rec)M}/dt$ vs. di_f/dt

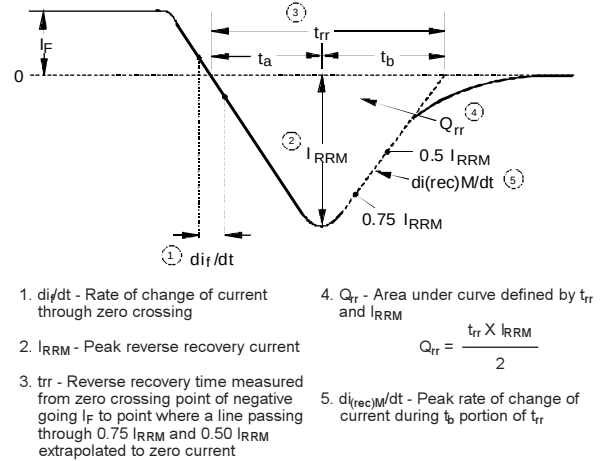
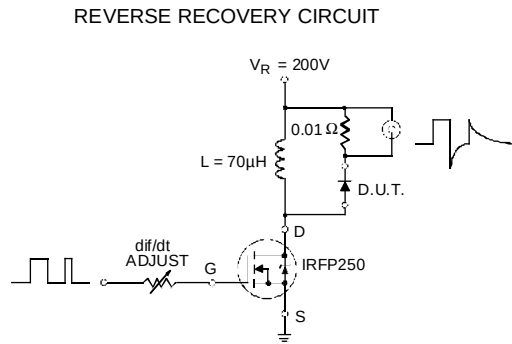


Fig. 9 - Reverse Recovery Parameter Test Circuit

Fig. 10 - Reverse Recovery Waveform and Definitions

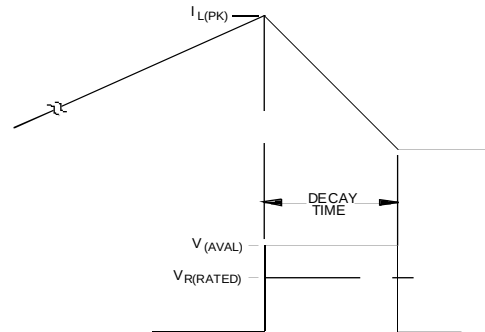
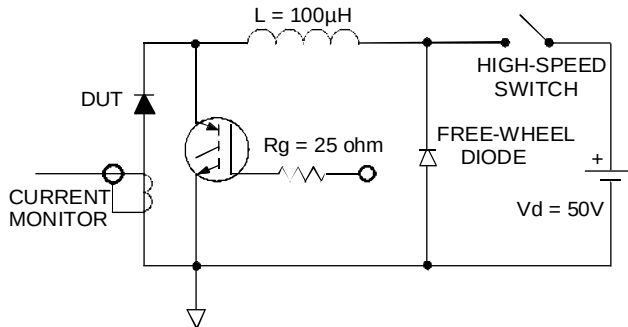


Fig. 11 - Avalanche Test Circuit and Waveforms